

Customer Process Change Notification Form PCN-2010-411

Part Information

Cirrus Logic Part # / Quantity

CS5381-KZZ/D CS5381-KZZR/D

PCN Effective Date:

Lot Effective Date:

Cirrus P/N Change: Yes No

(Contact the sales representative for availability of samples if applicable)

If yes, provide new part number:

Package Mark Change: Yes No

If Yes, briefly explain:

The assembly identifier will change from NA to AA. xxNAxxxxyyww to xxAAxxxxyyww Country of origin will change from Philippines to China.

[Any Fab, Assembly, or Design changes results in pack mark changes, please provide detail]

Reason for Change:

- | | |
|--|--|
| <input type="checkbox"/> Design/New Rev | <input type="checkbox"/> Fab Process |
| <input type="checkbox"/> Assembly Site | <input checked="" type="checkbox"/> Additional Assembly Source |
| <input type="checkbox"/> Fab Site | <input type="checkbox"/> Assembly Process |
| <input type="checkbox"/> Other (Specify) | <input type="checkbox"/> Additional Fab Source |

Description of Change:

- | | |
|---|--|
| <input type="checkbox"/> Fix Errata | <input type="checkbox"/> Yield Enhancement |
| <input type="checkbox"/> Fix Known Bug | <input type="checkbox"/> Performance Improvement |
| <input checked="" type="checkbox"/> Other (specify) | |

Addition of assembly site ANST (Wuxi, PRC) for the above listed devices assembled in 24 TSSOP. There will be no change to the other packaging bill of materials. Summary of Bill of Material Change: 24 TSSOP Current - Amkor New Site - ANST Mold Compound Sumitomo G700 No Change Die Attach Ablebond 8290 No Change Wire 1.0 mil Au No Change Leadframe 0.118" x 0.217" No Change Finish Matte Sn, 100% No Change

Quality and Reliability Impact:

Qualification Data Required? Yes No

RELIABILITY QUALIFICATION REPORT

Report Date: 10/22/2007

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Reliability Report: QRR071005

Subject/Purpose: This is to qualify 24LD and 28LD TSSOP built at ANST (China). This qualifies Pb-free material to MSL-3 with 260C peak reflow. This qualifies standard SnPb material to MSL-2 with 240C peak reflow.	APPROVALS: <div style="border: 1px solid black; padding: 2px; text-align: center;"> Michael Klucher Reliability Engineering </div>
Results: Qualification successful.	STATUS: Complete - Pass

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> (Fail/Sample)
Preconditioning MSL-3 QJ1391	24HR 125 °C Bake 192HR 30/60 °C/%RH Soak 3 pass 260 °C Convection reflow	JESD22-A113	Precondition	1	0/77
THB (post Precon MSL3 260C) QJ1391	85 °C 85 %RH 5.25 Volts	JESD22-A101	1000 Hours	1	0/77
Preconditioning MSL-2 QJ1392	24HR 125 °C Bake 168HR 85/60 °C/%RH Soak 3 pass 240 °C Convection reflow	JESD22-A113	Precondition	1	0/154
Tomography (post Precon MSL2 240C) QJ1392		J-STD-035	Post Precond	1	0/11

Background Information:

Part #: CS4272 (Similarity)	Rev: B	Fab: MagnaChip (F)	Lead Finish: Pb-free
Package: 28TSSOP (similarity)		Assembly: ANST (China)	

Prepared by: Genesis Krzyzaniak

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RELIABILITY QUALIFICATION REPORT

Report Date: 10/22/2007

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Reliability Report: QRR071005

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/sample)</u>
Preconditioning MSL-3 QJ1419	24HR 125 °C Bake 192HR 30/60 °C/%RH Soak 3 pass 260 °C Convection reflow	JESD22-A113-B	Precondition	1	0/154
			Precondition	2	0/154
			Precondition	3	0/154
TMCL-C (post Precon MSL3 260C) QJ1419	-65 °C +150 °C air to air	JESD22-A104	500 Cycles	1	0/77
			500 Cycles	2	0/77
			500 Cycles	3	0/77
Tomography (post Precon MSL3 260C) QJ1419		J-STD-035	Post Temp Cycle	1	0/11
			Post Temp Cycle	2	0/11
			Post Temp Cycle	3	0/11
Autoclave (post Precon MSL3 260C) QJ1419	121 °C 15 psig 100% R.H.	JESD22-A102	96 Hours	1	0/77
			96 Hours	2	0/77
			96 Hours	3	0/77
Solderability QJ1419	93 °C steam aging 8 Hours 245 °C solder bath 5 Seconds	JESD22-B102	Solderability	1	0/22
			Solderability	2	0/22
			Solderability	3	0/22
HTSL (high-temp storage life) QJ1419	150 °C	JESD22-A103	1000 Hours	1	0/77
			1000 Hours	2	0/77
			1000 Hours	3	0/77

Background Information:

Part #: CS4272 (Similarity)
Package: 28TSSOP (similarity)

Rev: B

Fab: MagnaChip (F)
Assembly: ANST (China)

Lead Finish: Pb-free

Prepared by: Genesis Krzyzaniak

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**RELIABILITY
QUALIFICATION
REPORT**

Report Date: 10/22/2007

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Reliability Report: QRR071005

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/sample)</u>
Preconditioning MSL-2 QJ1393	24HR 125 °C Bake	JESD22-A113-B	Precondition	1	0/154
	168HR 85/60 °C/%RH Soak 3 pass 240 °C Convection reflow		Precondition	2	0/154
TMCL-C (post Precon MSL2 240C) QJ1393	-65 °C +150 °C air to air	JESD22-A104	500 Cycles	1	0/77
			500 Cycles	2	0/77
Tomography (post Precon MSL2 240C) QJ1393		J-STD-035	Post Temp Cycle	1	0/11
			Post Temp Cycle	2	0/11
Autoclave (post Precon MSL2 240C) QJ1393	121 °C 15 psig 100% R.H.	JESD22-A102	96 Hours	1	0/77
			96 Hours	2	0/77

Background Information:

Part #: CS4272 (Similarity)
Package: 28TSSOP (similarity)

Rev: B

Fab: MagnaChip (F)
Assembly: ANST (China)

Lead Finish: Pb-free

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Data Sheet Change Required? Yes No

If Yes, briefly explain:

Software Change Required? Yes No

If Yes, briefly explain:

Customer Acknowledgement and Agreement

Acknowledged and Agreed as of the Date written below:

Customer Company _____
Name:


Customer Contact _____
Name:
Title: _____

Signature: _____

Date:

Customer Agreed Customer Reject Not Applicable

Customer Comments:

	Title: CUSTOMER PROCESS CHANGE NOTIFICATION FORM	Doc No: 4-QUAL-00017	Rev: D
	Digitally Signed By: Cirrus Logic - Customer Quality <small>Digitally signed by Cirrus Logic - Customer Quality DN: cn=Cirrus Logic - Customer Quality, c=US, ou=Cirrus Logic Austin, email=customer_quality@cirrus.com Reason: All signatures on file Date: 2010.10.13 10:23:49 -05'00'</small>		

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